

**Notice of References Cited**

Application/Control No.

09/763,891

Applicant(s)/Patent Under  
Reexamination  
UCHIDA ET AL.

Examiner

Lynette T. Umez-Eronini

Art Unit

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Luo et al., Chemical -Mechanical Polishing of Copper in Acidic Media, February 22-23, 1996, 1996 CMP-MIC Conference 1996 ISMIC - 100F/96/0145, pages 145-151.
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